

LINEAR TECHNOLOGY MATERIALS DECLARATION

1tc2668huj-16#trpbf

(Engineering Calculation)

QFN 6mm X 6mm Exp. Pad

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TOTAL MASS (g) : 0.113592

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.009899 | 1000000 | 87145.3125 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.043661 | 975000 | 384367.25 | | |
| | | Iron (Fe) | 7439-89-6 | 0.001075 | 24000 | 9463.70507812 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000013 | 300 | 114.444793701 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000031 | 700 | 272.906829834 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.044780 | 1000000 | 394218.3125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.004194 | 1000000 | 36920.6054688 | | |
| | | External Plating Total: | | | | 0.004194 | 1000000 | 36920.6054688 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000108 | 1000000 | 950.772216797 | | |
| Internal Plating Total: | | | | 0.000108 | 1000000 | 950.772216797 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.002927 | 750000 | 25767.6855469 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000976 | 250000 | 8592.16308594 | | |
| Die Attach Total: | | | | 0.003903 | 1000000 | 34359.8515625 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.006540 | 130000 | 57574.5351562 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.043267 | 860000 | 380898.71875 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000503 | 10000 | 4428.13330078 | | |
| | | Encapsulation Total: | | | | 0.050310 | 1000000 | 442901.375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000398 | 1000000 | 3503.77172852 | | |
| | | | | | TOTAL MASS (g) : | 0.113592 | | |